

1 We claim:

2 1. A method for annealing a structure formed by electrodeposition, the
3 method comprising:

4 providing the electrodeposition structure, the electrodeposition structure
5 comprising an electroformed mold, the electroformed mold having a nominal thickness
6 between and including 0.5mm to 8.0mm and having a melting temperature;

7 heating the electrodeposition structure to a temperature between ambient
8 temperature and the melting temperature of the electrodeposition structure;

9 isostatically pressurizing the electrodeposition structure to a pressure above
10 ambient pressure;

11 cooling the electrodeposition structure to ambient temperature; and

12 depressurizing the electrodeposition structure to ambient pressure.

13 2. An electroformed mold, the electroformed mold annealed at an annealing
14 temperature above ambient temperature and an annealing pressure above ambient
15 pressure; and

16 the electroformed mold comprising a material having an elongation measured at
17 break before and after annealing, the elongation at break after annealing being greater
18 than the elongation at break before annealing.

19 3. An electroformed mold, the electroformed mold comprising a material
20 having voids therein, at least a portion of the voids forming at least one protuberance on
21 the surface of the electroformed mold when the mold is exposed to heat;

1 the electroformed mold annealed at an annealing temperature above ambient
2 temperature and an annealing pressure above ambient pressure; and

3 the number of voids forming protuberances on the surface of the electroformed
4 mold being reduced after annealing of the electroformed mold as compared to before
5 annealing of the electroformed mold.

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